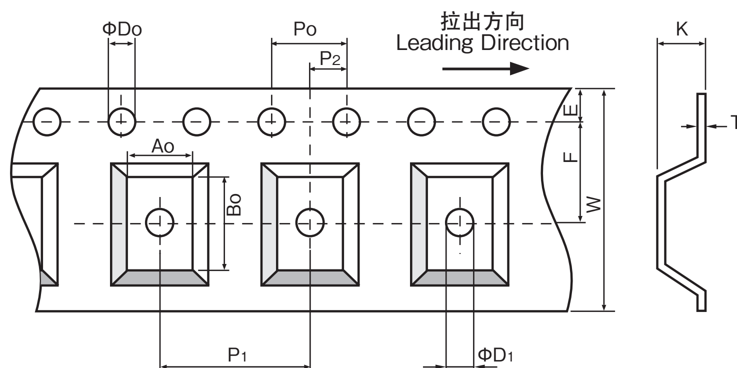
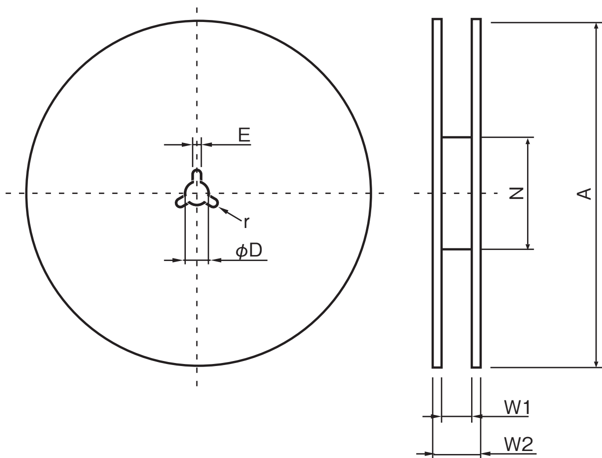
◆ 编带尺寸／CARRIER TAPE DIMENSIONS



贴片尺寸 Chip size	编码 Taping code	尺寸 Dimensions [mm]											
		A0 ±0.1	B0 ±0.1	W ±0.2	F ±0.05	E ±0.1	P1 ±0.1	P2 ±0.05	P0 ±0.1	ϕD0 ±0.1	ϕD1 +0.2/-0	K ±0.1	T ±0.05
1608	Y 1	1.1	1.9	8.0	3.5	1.75	4.0	2.0	4.0	1.5	—	0.8	0.20
2012	Z 1	1.45	2.25	8.0	3.5	1.75	4.0	2.0	4.0	1.5	1.0	1.0	0.25
	Z 2											1.3	0.25
3216 1632	A 1	1.9	3.5	8.0	3.5	1.75	4.0	2.0	4.0	1.5	1.1	1.4	0.30
	A 2											1.8	0.30
3225	B 1	2.8	3.5	8.0	3.5	1.75	4.0	2.0	4.0	1.5	1.0	1.8	0.30
	B 2											2.2	0.30
	B 3											2.4	0.30
4532 3245	C 1	3.6	4.9	12.0	5.5	1.75	8.0	2.0	4.0	1.5	1.5	1.8	0.30
	C 2											2.2	0.30
	C 3											2.4	0.30
	C 4											3.0	0.30
5750	D 1	5.3	6.0	12.0	5.5	1.75	8.0	2.0	4.0	1.5	1.6	2.2	0.30
	D 2											2.6	0.30
	D 3											3.0	0.30

◆ 卷筒尺寸／REEL DIMENSIONS

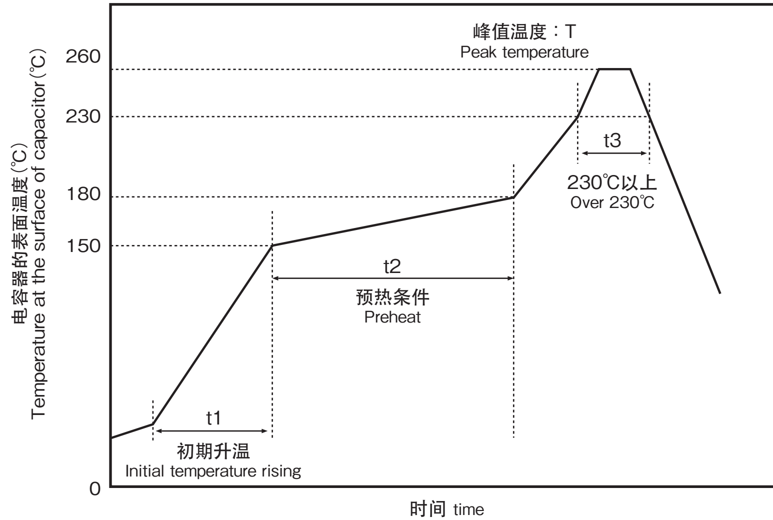


贴片尺寸 Chip size	编码 Taping code	卷筒尺寸 Reel size	包装数量 Quantity
1608	Y1	ϕ180mm	4,000pcs/reel
2012	Z1, Z2	ϕ180mm	3,000pcs/reel
3216 1632	A1	ϕ180mm	3,000pcs/reel
	A2	ϕ180mm	2,000pcs/reel
3225	B1, B2, B3	ϕ180mm	2,000pcs/reel
4532 3245	C1, C2	ϕ180mm	1,000pcs/reel
	C3, C4	ϕ180mm	500pcs/reel
5750	D1, D2	ϕ180mm	1,000pcs/reel
	D3, D4	ϕ180mm	500pcs/reel

编码 Taping code	尺寸 Dimensions [mm]						
	A ±1.0	N ±1.0	W1 ±1.0	W2 ±1.0	ϕD ±0.2	E ±0.5	r ±0.2
Y, Z, A, B	180	60	9.5	13.1	13.0	2.0	1.0
C, D	180	60	13.5	18.5	13.0	2.0	1.0

●电路板焊接条件／SOLDERING CONDITIONS

◆回流焊接条件／REFLOW SOLDERING CONDITIONS MU series/MS series/MR series/ST series



初期升温区间：t1 Period of initial temperature rising	预热区间：t2 Period of preheat	230℃以上区间: t3 Period over 230℃	峰值温度：T Peak temperature
常温 (room temperature) ～150℃ 3℃/ sec MAX	150～180℃ 60～120 sec	30～60 sec	260℃ MAX

※测定温度的位置为电容器层积的表面。Temperature is measured at the surface of capacitor.

1）请尽量缩短停留在峰值温度的时间。
Holding time at the peak temperature should be as short as possible.

2）重复进行回流焊的次数为2次，且第二回的回流焊必须等到电容器温度恢复到常温后再实施。
Reflow soldering cycle is limited to two (2). The second soldering should be done after the capacitor itself has returned to room temperature.

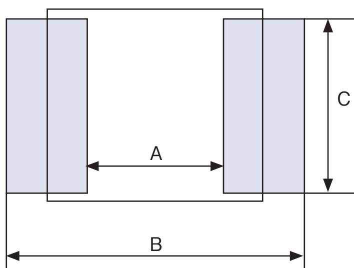
3）与我公司推荐回流焊温度曲线不同时，请与我公司联系。
Please consult us in advance if your reflow soldering condition is different from recommended condition.

◆自动焊接条件／FLOW SOLDERING CONDITIONS MU series/MS series/MR series/LDT series

关于自动焊接条件，请联系我们。
Please consult us about flow soldering conditions.

◆推荐焊盘尺寸／RECOMMENDED LAND SIZE MU series/MS series/MR series/ST series

电容器焊接所使用的焊盘尺寸请尽量使用下表的设计值。
但是、波峰焊实装时的B尺寸要比下表的尺寸大0.4～0.6mm。
若焊盘设计值与推荐值相差较大时，请另行联系我们。
For designing land size, refer to the following recommended land size.
However, in flow soldering, please enlarge B dimension about 0.4 to 0.6 mm.
Please consult us in advance if your land desing is vastly different from recommended land size.



贴片形状 Chip size	焊盘尺寸记号(mm) Dimensions		
	A	B	C
1608	0.5	2.0	0.7
2012	0.8	2.4	1.1
3216	1.8	3.6	1.4
3225	1.8	3.6	2.3
4532	2.7	5.7	3.0
5750	3.5	7.8	4.5
1632	0.5	2.2	3.0
3245	1.8	3.6	4.1